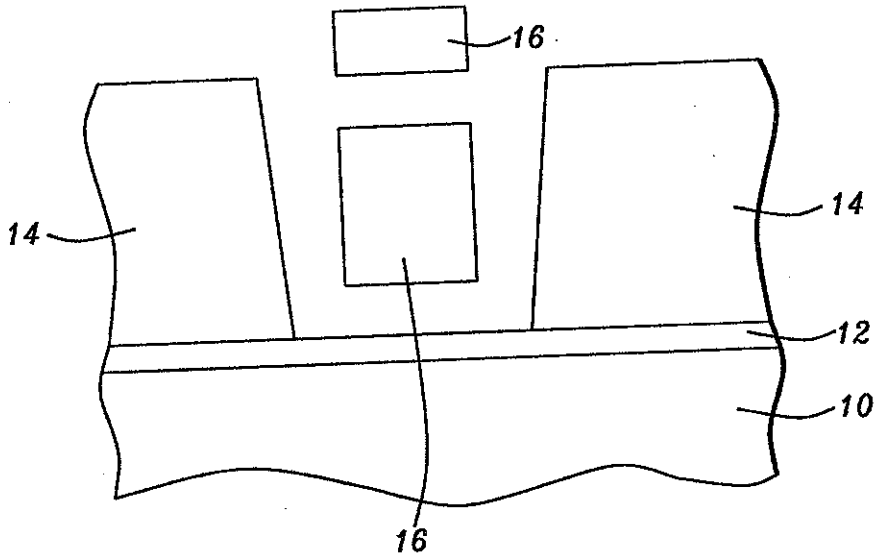


FIG. 1

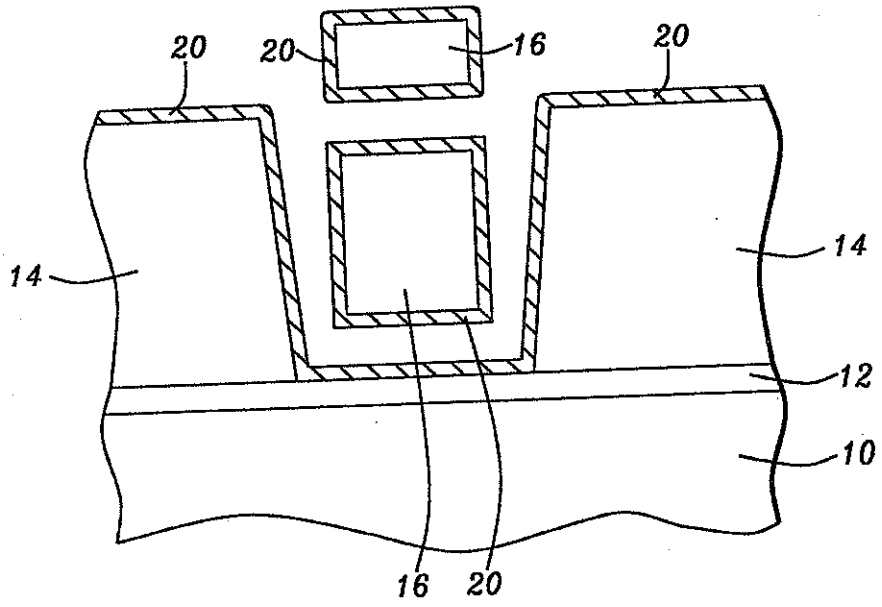


FIG. 2

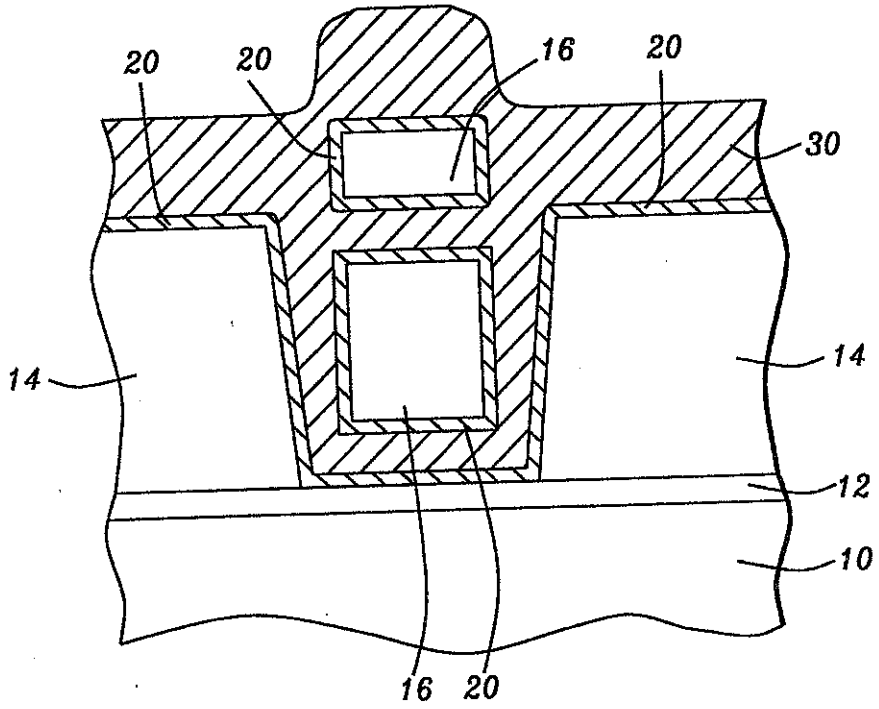


FIG. 3

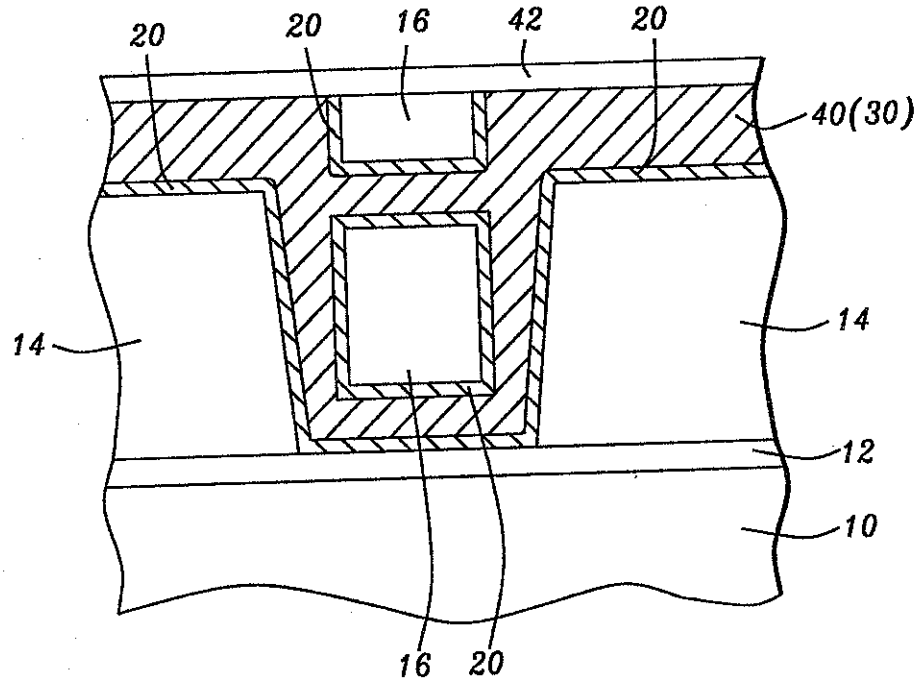


FIG. 4

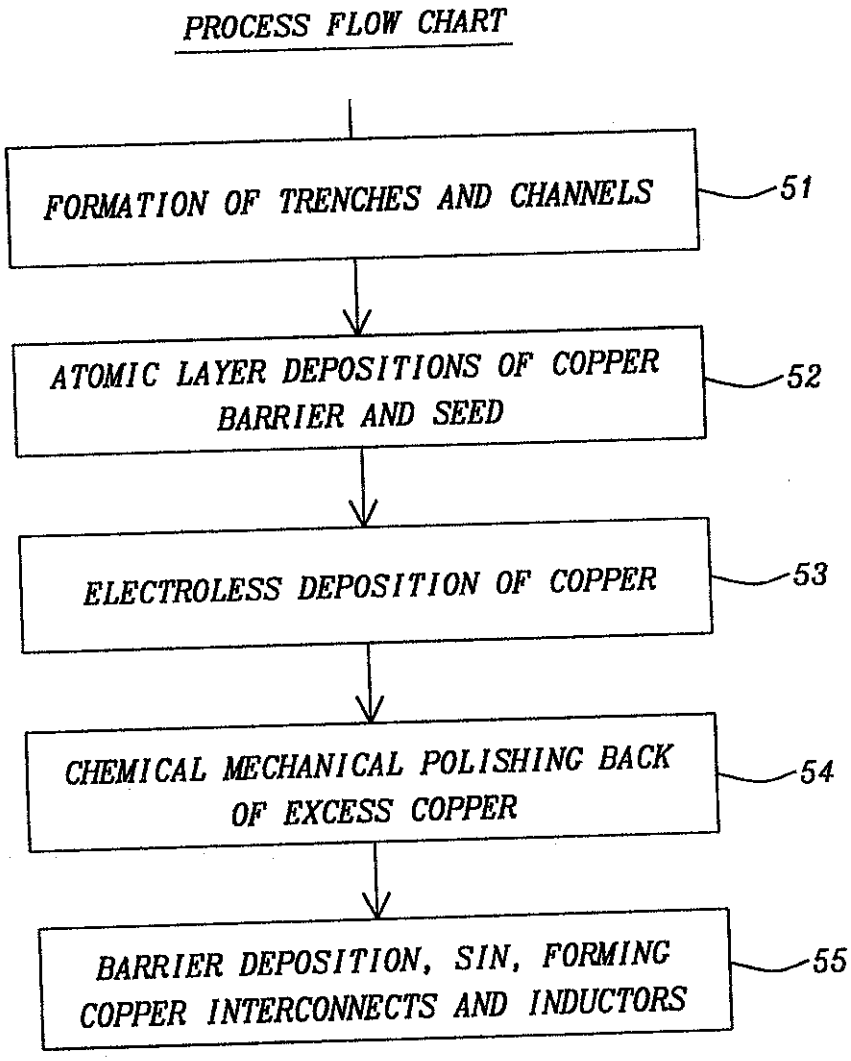

PROCESS FLOW CHART
FORMATION OF TRENCHES AND CHANNELS
51
ATOMIC LAYER DEPOSITIONS OF COPPER BARRIER AND SEED
52
ELECTROLESS DEPOSITION OF COPPER
53
CHEMICAL MECHANICAL POLISHING BACK OF EXCESS COPPER
54
BARRIER DEPOSITION, SIN, FORMING COPPER INTERCONNECTS AND INDUCTORS
55

FIG. 5